

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-3. (Canceled)

4. (Currently Amended) A semiconductor device comprising:

a substrate;

an adhesive material comprising a resin over the substrate;

a protective film over the adhesive material, said protective film comprising
Teflon;

an insulating film over the protective film; and

a thin film transistor over the insulating film.

5. (Previously Presented) A semiconductor device according to claim 4, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.

6.-19. (Canceled)

20. (Currently Amended) A semiconductor device comprising:

a substrate;

an adhesive material comprising a resin over the substrate; and

a protective film over the adhesive material, said protective material comprising

Teflon;

an insulating film over the protective film;

a central processing unit comprising a control section and an operation section,
and a memory unit over the insulating film; and
a battery over the substrate;
wherein the central processing unit includes a thin film transistor of n-channel
type and a thin film transistor of p-channel type.

21.-27. (Canceled)

28. (Currently Amended) A semiconductor device comprising:
a plastic substrate;
an adhesive material comprising a resin over the plastic substrate; and
a protective film over the adhesive material, said protective film comprising a
material selected from the group consisting of SnO₂, SrO, Teflon, and metal;
an insulating film over the protective film, said insulating film comprising silicon
oxynitride;
a central processing unit comprising a control section and an operation section,
and a memory unit over the insulating film; and
a battery over the plastic substrate;
wherein the central processing unit includes a thin film transistor of n-channel
type and a thin film transistor of p-channel type.

29. (Currently Amended) A semiconductor device comprising:
a plastic substrate;
an adhesive material comprising a resin over the plastic substrate; and
a protective film over the adhesive material, said protective film comprising a
material selected from the group consisting of SnO₂, SrO, Teflon, and metal;
an insulating film over the protective film;

a central processing unit comprising a control section and an operation section, and a memory unit over the insulating film; and

wherein the central processing unit includes a thin film transistor of n-channel type and a thin film transistor of p-channel type.

30. (Previously Presented) A semiconductor device according to claim 28, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.

31. (Previously Presented) A semiconductor device according to claim 29, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.

32. (New) A semiconductor device according to claim 20, wherein the semiconductor device is an authentication card, a video camera, a digital camera, a goggle type display, a car navigation system, a personal computer, or a mobile information terminal.